

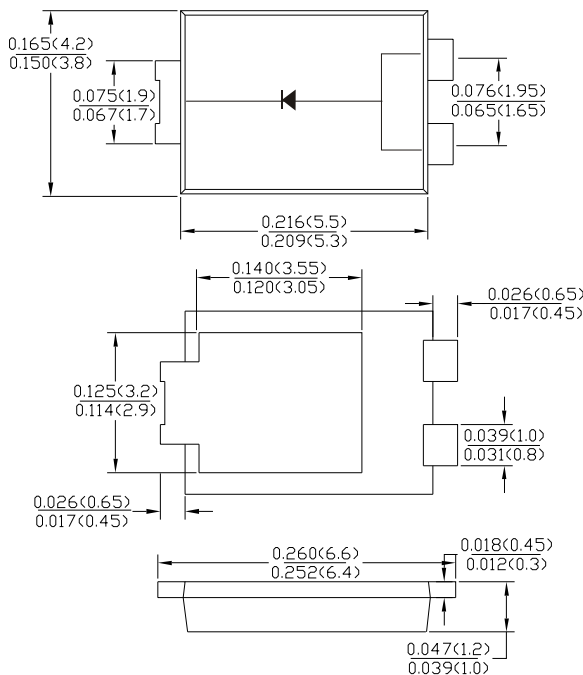
Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Fow Power Loss,High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277, molded plastic
- Terminals:Plated Leads Solderable per MIL-STD-202,Method 208
- Polarity:Cathode Band
- Mounting Position:Any
- Marking:Type Number
- Lead Free:For RoHS/Lead Free Version

TO-277



Dimiensions inches and (milimenters)

Maximum Ratings and Electrical Characteristics @T_A =25 °C unless otherwise specified

Single Phase,half wave,60Hz,resistive or inductive load.For capacitive load,derate current by 20%.

Parameter	Symbol	SL 0540	SL 0545	SL 0550	SL 0560	SL 0580	SL 05100	SL 05150	SL 05200	Unit
Peak Repetitive Reverse Voltage	V _{RRM}									V
Working Peak Reverse Voltage	V _{RWM}	40	45	50	60	80	100	150	200	V
DC blocking voltage	V _{DC}									V
RMS Rectified Voltage	V _{R(RMS)}	28	32	35	42	56	70	105	140	V
Average Rectified Output Current (Note1)	I _o	5.0								A
Non-Repetitive Peak Forward Surge8.3ms Single Half Sine-Wave Superimposed on rated load(JEDEC Method) (Note2)	I _{FSM}	130								A
Forward Voltage Drop T _A =25 °C @IF=5A	V _{FM}	0.52		0.68		0.82		0.85	0.90	V
Peak Reverse Curent T _A =25 °C At Rated DC Blocking Voltage T _A =100 °C	I _R	0.3 15								mA
Typical Thermal Resistance Junctionto Ambient	R _{θJA} R _{θJL}	80 15								°C/W
Operating junction temperature range	T _J	-55 to +150								°C
storage temperature range	T _{STG}	-55 to +150								°C

Note:1.Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2.Fr-4pcb.2oz.Copper,minimum recommend pad layout .18.8mm×14.4.Anode pad dimensions 5.6mm×14.4mm.

Fig.1 - Forward Current Derating Curve

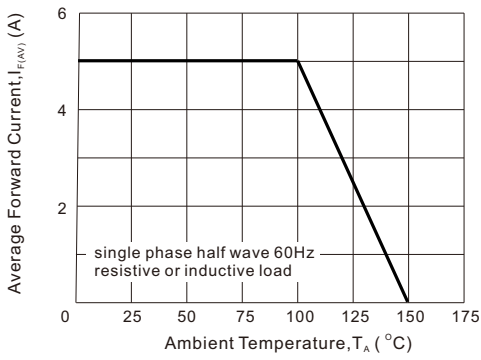


Fig2 : Instantaneous Forward Voltage

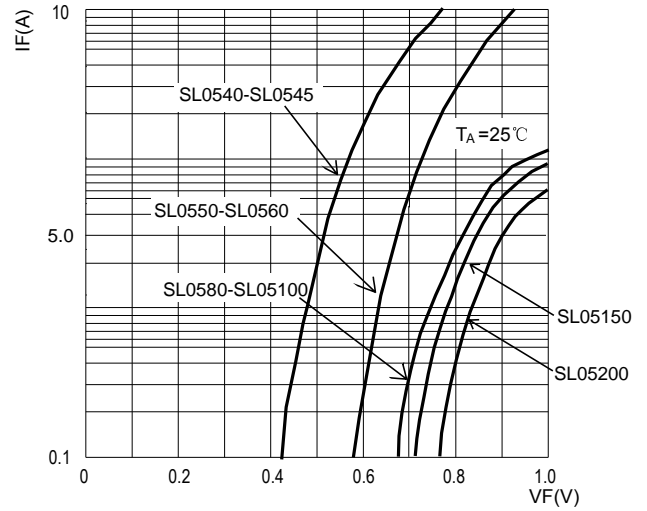


Fig3: Surge Forward Current Capadility

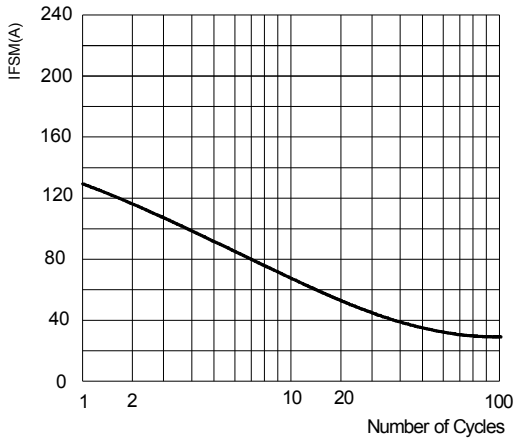


Fig4: Typical Reverse Characteristics

